

ABSTRACT OF THE DISCLOSURE

A surface-mounted light-emitting diode can be employed as a light source for cell phones and other electronic devices and contributes to the downsizing of electronic devices. An optically transmissive resin can have a surface provided with metallic films formed thereon and be employed to seal an LED chip and wires therein. The LED chip can be mounted on the metallic film via a conductive adhesive to achieve an electrical connection between a lower electrode of the LED chip and the metallic film. The wires can be connected between upper electrodes of the LED chip and the metallic films to achieve electrical conduction between the upper electrodes of the LED chip and the metallic films.